



PK150 (v1.3) July 27, 2017

100% Material Declaration Data Sheet for FS48

Average Weight : 0.0967 g

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight (in grams)	Component % of total
Silicon die	Silicon	7440-21-3	100.00		0.005900	6.10%
					0.005900	
Die Attach	Silver	7440-22-4	75.00	Filler	0.001538	2.12%
	Epoxy Resin	29690-82-2	25.00		0.000513	
Bonding Wire	Gold	7440-57-5	100.00	Wire	0.000950	0.98%
					0.000950	
Mold compound	Epoxy	29690-82-2	26.5		0.011302	44.11%
	Carbon Black	1333-86-4	0.5		0.000213	
	Silica	60676-86-0	70		0.029855	
	Antimony Trioxide	1309-64-4	2		0.000853	
	Brominated Flame Retardant (TBBA)	79-94-7	1	Flame Retardant	0.000427	
Solder Ball	Tin	7440-31-5	63.00	Base metal	0.008316	13.65%
	Lead	7439-92-1	37.00	Base metal	0.004884	
Substrate					0.032197	33.30%
	Copper	7440-50-8	38.00		0.012235	
	Nickel	7440-02-0	1.24		0.000401	
	Gold	7440-57-5	0.16		0.000052	
	Core	N/A	44.72		0.014400	
	Solder Mask	N/A	15.87		0.005109	

Revision History

Date	Version	Description of Revisions
4/6/2006	1.0	Initial Xilinx release.
7/28/2006	1.1	100% Material Declaration
9/29/2006	1.2	Updated component description
7/27/2017	1.6	Updated Substrate component, per XCN17007

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